

零件材料成分表

Type: Chip Array

部位名	材料名	CAS No.	成分	重量比率%	使用目的	備考
Substrate	Alumina	1344-28-1	Al ₂ O ₃	98%	Raw material	
		14808-60-7	SiO ₂	<3%	Raw material	
		1309-48-4	MgO	<2%	Raw material	
Top Electrode	Silver Paste	7440-22-4	Ag	80~90%	Electricity Conductivity	
		7440-05-3	Pd	1~1.5%	Raw material	
		8000-41-7	Terpineol	5~10%	Adhesion	
Bottom Electrode	Silver Paste	7440-22-4	Ag	45~55%	Electricity Conductivity	
		1317-38-0	CuO	1~10%	Raw material	
		112-34-5	butyl Carbitol	10~20%	Adhesion	
		8000-41-7	Terpineol	5~15%	Adhesion	
Edge Electrode	Silver Paste	7440-22-4	Ag	78~81%	Electricity Conductivity	
			Epoxy Resin	6~18%	Adhesion	
			Additives	1~5%	Additives	
Resistor	Resistor Paste	12036-10-1	R ₂ O ₂	5~30%	Electricity Conductivity	
		7440-05-3	Pd	10~20%	Electricity Conductivity	
		1317-38-8	PbO	5~30%	Adhesion	
		7440-22-4	Ag	10~20%	Raw material	
		1314-13-2	ZnO	<5%	Adhesion	
Plating	Plating Chemical Tin ball Nickel cake	7440-31-5	Sn	20~50%	Solder	
		7440-02-0	Ni	20~50%	Raw material	
Primary Overcoat	Dielectric Paste	65997-18-4	Frits	65~70%	Adhesion	
		124-17-4	butyl Carbitol acetate	20~25%	Adhesion	
		9004-67-3	Resin	1~5%	Adhesion	
		1308-38-9	Cr ₂ O ₃	<1%	Coloring	
Secondary Overcoat	Black Paste		Resin	16~28%	Adhesion	
			Filler	28~38%	Filler	
			Additives	6~17%	Additives	
			Pigment	6~17%	Coloring	
Marking	White Paste		Resin	30~80%	Adhesion	
			Pigment	0~30%	Coloring	